EMZ1DXV6T1, EMZ1DXV6T5

Dual General Purpose Transistors

NPN/PNP Dual (Complementary)

This transistor is designed for general purpose amplifier applications. It is housed in the SOT–563 which is designed for low power surface mount applications.

Features

- Lead–Free Solder Plating
- Low $V_{CE(SAT)}$, <0.5 V
- These are Pb–Free Devices

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-60	V
Collector – Base Voltage	V _{CBO}	-50	V
Emitter-Base Voltage	V _{EBO}	-6.0	V
Collector Current – Continuous	Ι _C	-100	mAdc

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D	357 (Note 1) 2.9 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	°C/W
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D	500 (Note 1) 4.0 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	250 (Note 1)	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

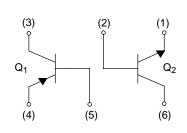
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ Minimum Pad.



ON Semiconductor®

http://onsemi.com





SOT-563 CASE 463A STYLE 1

MARKING DIAGRAM



3Z = Specific Device Code M = Month Code = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

EMZ1DXV6T1, EMZ1DXV6T5

ELECTRICAL CHARACTERISTICS (T_A = 25° C)

Characteristic	Symbol	Min	Тур	Max	Unit
Q1: PNP			-		-
Collector–Base Breakdown Voltage ($I_C = -50 \mu Adc, I_E = 0$)	V _{(BR)CBO}	-60	-	-	Vdc
Collector–Emitter Breakdown Voltage ($I_C = -1.0 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	-50	-	-	Vdc
Emitter–Base Breakdown Voltage (I _E = –50 μAdc, I _E = 0)	V _{(BR)EBO}	-6.0	-	-	Vdc
Collector-Base Cutoff Current ($V_{CB} = -30 \text{ Vdc}, I_E = 0$)	I _{CBO}	-	-	-0.5	nA
Emitter–Base Cutoff Current (V _{EB} = -5.0 Vdc, I _B = 0)	I _{EBO}	-	-	-0.5	μΑ
Collector–Emitter Saturation Voltage (Note 2) ($I_C = -50$ mAdc, $I_B = -5.0$ mAdc)	V _{CE(sat)}	_	-	-0.5	Vdc
DC Current Gain (Note 2) ($V_{CE} = -6.0$ Vdc, $I_C = -1.0$ mAdc)	h _{FE}	120	-	560	_
Transition Frequency ($V_{CE} = -12$ Vdc, $I_C = -2.0$ mAdc, f = 30 MHz)	f _T	_	140	-	MHz
Output Capacitance (V _{CB} = -12 Vdc, I _E = 0 Adc, f = 1 MHz)	C _{OB}	-	3.5	-	pF
Q2: NPN					
Collector-Base Breakdown Voltage $(I_C = 50 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	60	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 1.0$ mAdc, $I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = 50 \ \mu Adc, I_E = 0$)	V _{(BR)EBO}	7.0	-	-	Vdc
Collector-Base Cutoff Current ($V_{CB} = 60 \text{ Vdc}, I_E = 0$)	I _{CBO}	-	-	0.5	μΑ
Emitter-Base Cutoff Current ($V_{EB} = 7.0 \text{ Vdc}, I_B = 0$)	I _{EBO}	-	-	0.5	μΑ
Collector-Emitter Saturation Voltage (Note 3) ($I_C = 50$ mAdc, $I_B = 5.0$ mAdc)	V _{CE(sat)}	_	_	0.4	Vdc
DC Current Gain (Note 3) (V _{CE} = 6.0 Vdc, I _C = 1.0 mAdc)	h _{FE}	120	_	560	-
Transition Frequency (V _{CE} = 12 Vdc, I _C = 2.0 mAdc, f = 30 MHz)	f _T	-	180	-	MHz
Output Capacitance (V _{CB} = 12 Vdc, I _C = 0 Adc, f = 1 MHz)	C _{OB}	-	2.0	-	pF

Pulse Test: Pulse Width ≤ 300 μs, D.C. ≤ 2%.
 Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

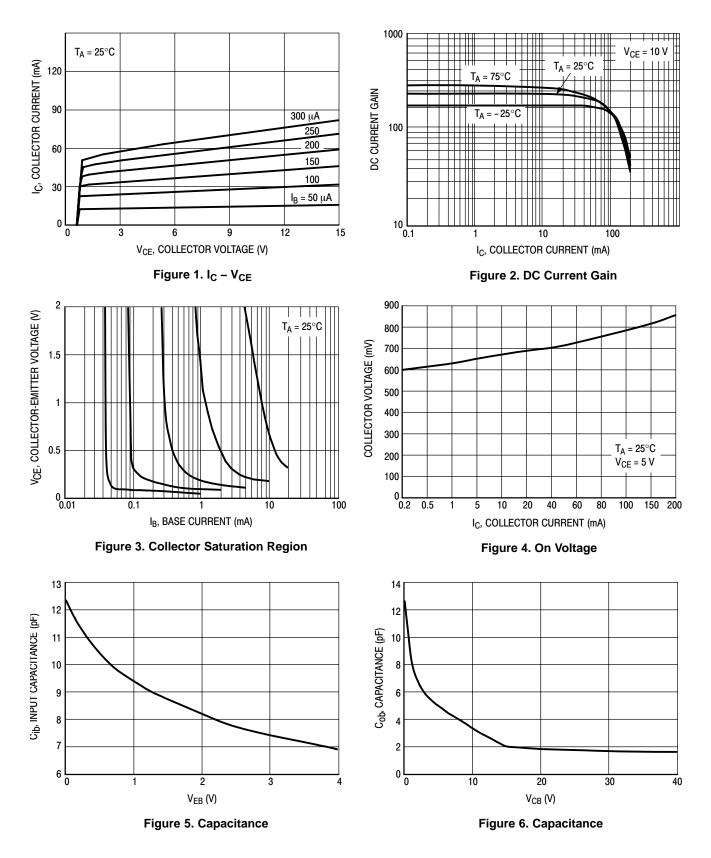
ORDERING INFORMATION

Device	Package	Shipping [†]	
EMZ1DXV6T1	SOT-563*	4000 Units / Tape & Reel	
EMZ1DXV6T1G	SOT-563*	4000 Units / Tape & Reel	
EMZ1DXV6T5	SOT-563*	8000 Units / Tape & Reel	
EMZ1DXV6T5G	SOT-563*	8000 Units / Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

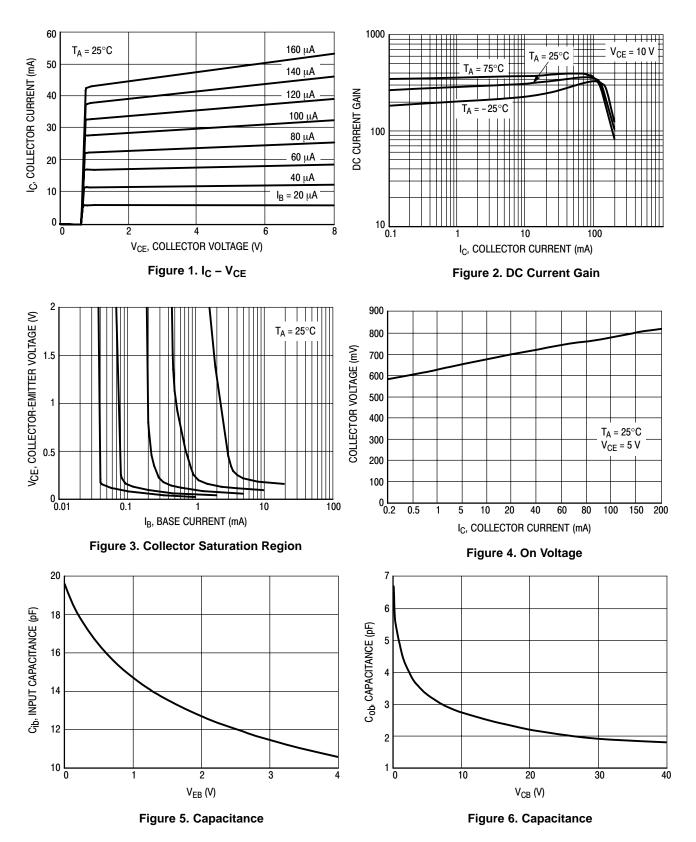
EMZ1DXV6T1, EMZ1DXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS – Q1, PNP



EMZ1DXV6T1, EMZ1DXV6T5

TYPICAL ELECTRICAL CHARACTERISTICS – Q2, NPN





SOT-563-6 1.60x1.20x0.55, 0.50P CASE 463A ISSUE J DATE 15 FEB 2024 NOTES: 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018. 2. ALL DIMENSION ARE IN MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM 3 THICKNESS OF BASE MATERIAL. -A D MILLIMETERS А 6X L DIM В MIN NDM. MAX. m 0.50 0.55 А 0.60 ł 6 4 PIN b 0.17 0.22 0.27 F Н REFERENCE \subset 0.08 0.13 0.18 2 ັບ 1 3 D 1.50 1.60 1.70 Ε 1.20 1.30 1.10 -⊨ 6X b C ⊕ 0.08∭ A B е 0.50 BSC е Н 1.50 1.60 1.70 TOP VIEW SIDE VIEW L 0.10 0.20 0.30 1.30 6X 0.45 0.30 1.80 STYLE 1: STYLE 2 STYLE 3 PIN 1. EMITTER 1 2. BASE 1 PIN 1. EMITTER 1 PIN 1. CATHODE 1 2. CATHODE 1 2. EMITTER 2 3. COLLECTOR 2 3. BASE 2 3. ANDDE/ANDDE 2 4. EMITTER 2 4. COLLECTOR 2 4. CATHODE 2 0.50 5. BASE 2 5. BASE 1 5. CATHODE 2 6. COLLECTOR 1 PITCH 6. COLLECTOR 1 6. ANDDE/ANDDE 1 RECOMMENDED MOUNTING FOOTPRINT* STYLE 6: PIN 1. CATHODE 2. ANODE FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE STYLE 5 STYLE 4: 1. CATHODE 2. CATHODE PIN 1. COLLECTOR PIN 2. COLLECTOR 3. BASE 3. ANDDE 3. CATHODE 4. ANDDE 5. CATHODE 4. CATHODE 5. CATHODE 4. EMITTER MANUAL, SOLDERRM/D. 5, COLLECTOR 6. COLLECTOR 6. CATHODE 6. CATHODE GENERIC **MARKING DIAGRAM*** STYLE 7: STYLE 8 STYLE 9 PIN 1. CATHODE PIN 1. DRAIN PIN 1. SOURCE 1 2. ANDDE 2. DRAIN 2. GATE 1 XXM. 3. CATHODE 4. CATHODE 3. GATE 4. SDURCE 5. DRAIN 3. DRAIN 2 4. SDURCE 2 5. GATE 2 1 5. ANDDE 6. CATHODE 6. DRAIN 6. DRAIN 1 XX = Specific Device Code M = Month Code = Pb-Free Package STYLE 10: STYLE 11: *This information is generic. Please refer to PIN 1. CATHODE 1 PIN 1. EMITTER 2 device data sheet for actual part marking. 2. N/C 3. CATHODE 2 2. BASE 2 3. COLLECTOR 1 Pb-Free indicator, "G" or microdot "•", may 4. ANDDE 2 EMITTER 1 4. or may not be present. Some products may BASE 5. N/C 5. not follow the Generic Marking. 6. ANDDE 1 COLLECTOR 2 6. Electronic versions are uncontrolled except when accessed directly from the Document Repository. **DOCUMENT NUMBER:** 98AON11126D Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** SOT-563-6 1.60x1.20x0.55, 0.50P PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent_Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>